

# N-Channel Enhancement Mode MOSFET

TDM3478

## DESCRIPTION

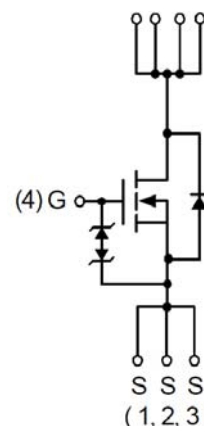
The TDM3478 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. This device is suitable for use as a load switch or in PWM applications.

## GENERAL FEATURES

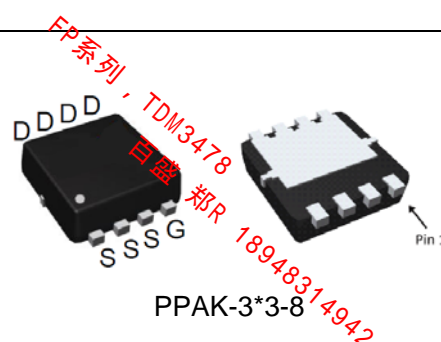
- $R_{DS(ON)} < 9.7m\Omega$  @  $V_{GS}=4.5V$   
 $R_{DS(ON)} < 6m\Omega$  @  $V_{GS}=10V$
- High Power and current handling capability
- ESD Protection
- Surface Mount Package
- Lead Free and Green Devices available(RoHS Compliant)

## Application

- PWM applications
- Load switch
- Power management
- Powered Systems



N-Channel MOSFET



## ABSOLUTE MAXIMUM RATINGS( $T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current @ Continuous	$I_D$ ( $T_c=25^{\circ}C$ )	54	A
	$I_D$ ( $T_c=100^{\circ}C$ )	34	
Drain Current @ Current-Pulsed (Note 1)	$I_{DP}$ ( $T_c=25^{\circ}C$ )	100	
Maximum Power Dissipation	$P_D$ ( $T_c=25^{\circ}C$ )	26.6	W
	$P_D$ ( $T_c=100^{\circ}C$ )	10.6	
Drain Current @ Continuous	$I_D$ ( $T_A=25^{\circ}C$ )	15.2	A
	$I_D$ ( $T_A=70^{\circ}C$ )	12.1	
Maximum Power Dissipation	$P_D$ ( $T_A=25^{\circ}C$ )	2.08	W
	$P_D$ ( $T_A=70^{\circ}C$ )	1.3	
Thermal Resistance,Junction-to-Ambient (Note 2)	$R_{\theta JA}(t \leq 10s)$	40	$^{\circ}C/W$
	$R_{\theta JA}(\text{Steady State})$	60	
Thermal Resistance,Junction-to-Case	$R_{\theta JC}(\text{Steady State})$	4.7	$^{\circ}C/W$
Maximum Operating Junction Temperature	$T_J$	150	$^{\circ}C$
Storage Temperature Range	$T_{STG}$	-55 To 150	$^{\circ}C$

**N-Channel Enhancement Mode MOSFET**
**TDM3478**
**ELECTRICAL CHARACTERISTICS ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

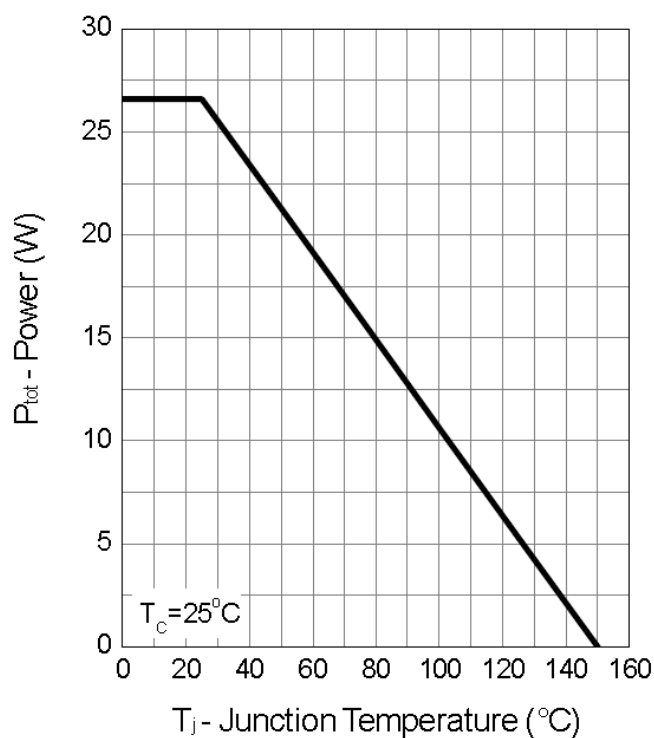
Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =24V,V <sub>GS</sub> =0V	-	-	1	μ A
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±10	μ A
ON CHARACTERISTICS						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	1.4	1.7	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =9A	-	7.5	9.7	mΩ
		V <sub>GS</sub> =10V, I <sub>D</sub> =12A	-	5	6	
		T <sub>J</sub> =125℃	-	7.6	-	
DYNAMIC CHARACTERISTICS (Note3)						
Gate Resistance	R <sub>G</sub>	V <sub>GS</sub> =0V,V <sub>DS</sub> =0V,F=1MHz	-	1.8	3	Ω
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V, F=1.0MHz	-	750	-	PF
Output Capacitance	C <sub>oss</sub>		-	530	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	37	-	PF
SWITCHING CHARACTERISTICS (Note 3)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =15V, R <sub>L</sub> =15Ω, V <sub>GEN</sub> =10V,R <sub>G</sub> =1Ω I <sub>D</sub> =1A	-	7.8	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	8.4	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	18	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	17	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =15V,I <sub>D</sub> =12A,V <sub>GS</sub> =4.5V	-	5.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.9	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	2.2	-	nC
Body Diode Reverse Recovery Time	T <sub>rr</sub>	I <sub>F</sub> =5A, dI/dt=100A/μs	-	11	-	nS
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	13	-	nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode Forward Voltage (Note 2)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =10A	-	0.8	1.1	V

**NOTES:**

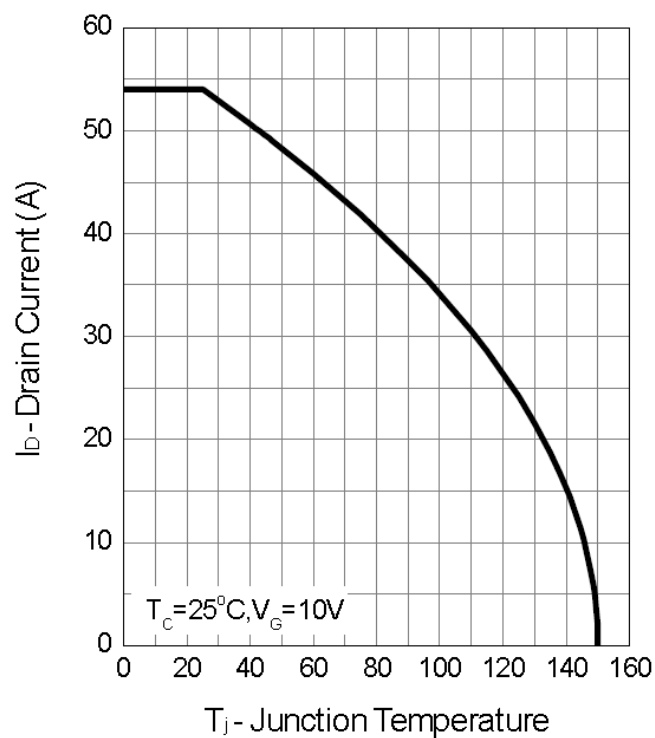
- Pulse width limited by max. junction temperature.
- $R_{\theta JA}$  steady state=999s.  $R_{\theta JA}$  is measured with the device mounted on 1in2, Fr-4 board with 2oz.Copper
- Guaranteed by design, not subject to production testing

## Typical Operating Characteristics

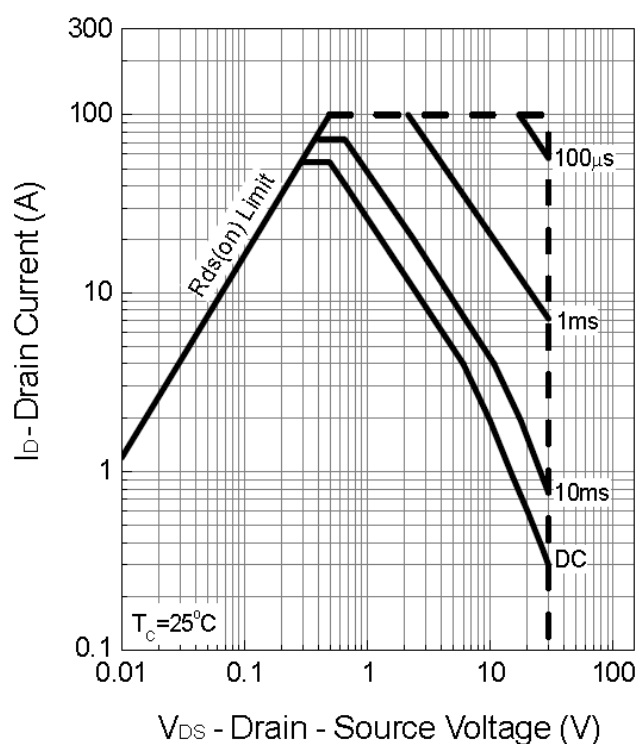
Power Dissipation



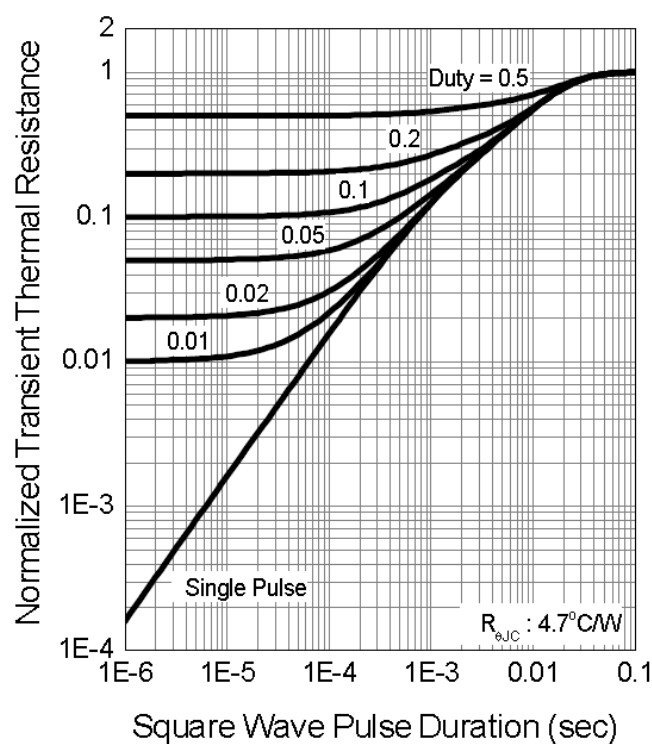
Drain Current



Safe Operation Area

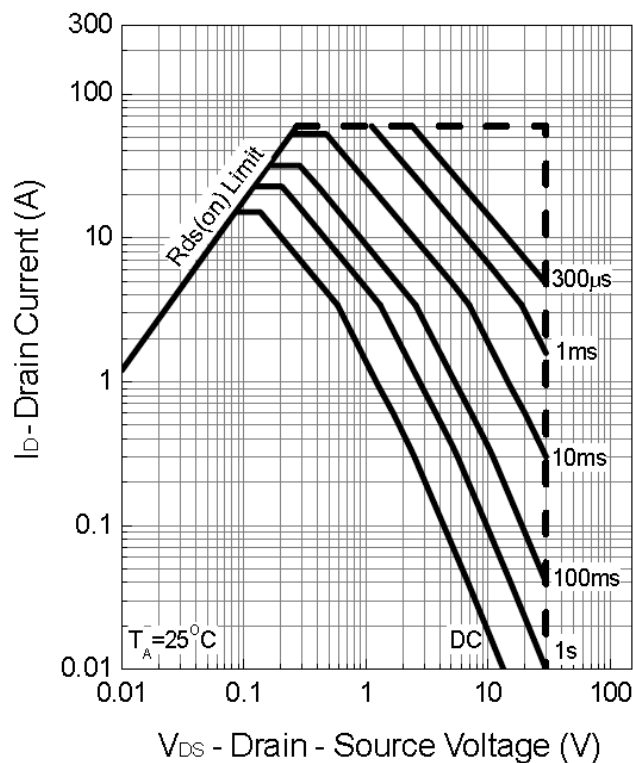


Thermal Transient Impedance

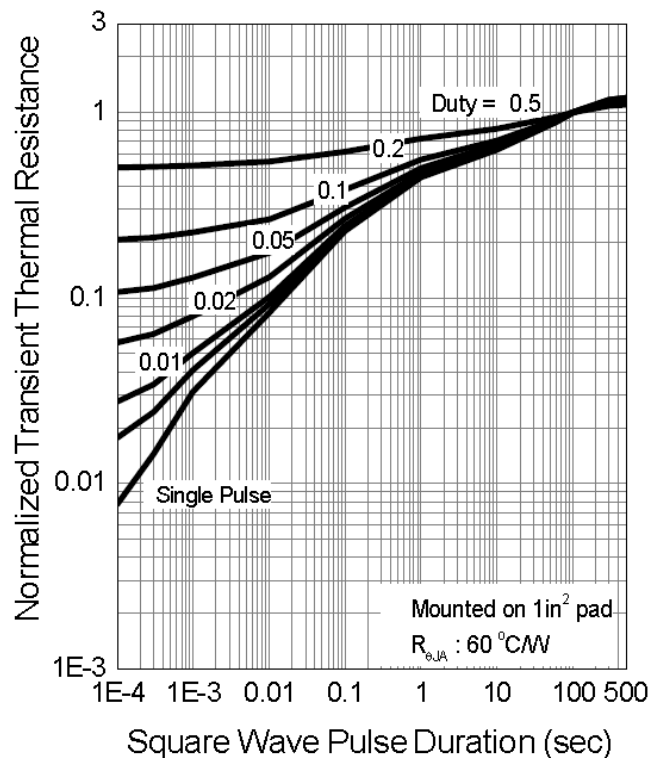


## Typical Operating Characteristics(Cont.)

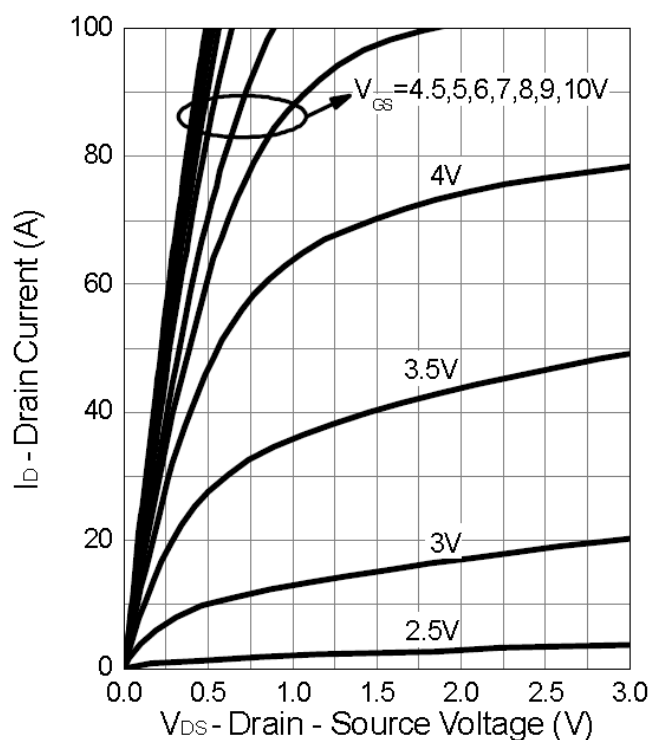
Safe Operation Area



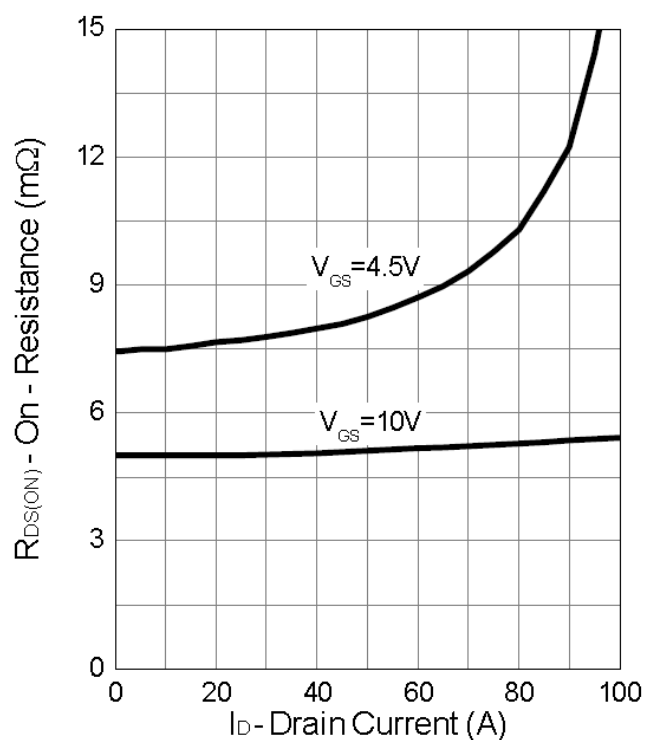
Thermal Transient Impedance



Output Characteristics

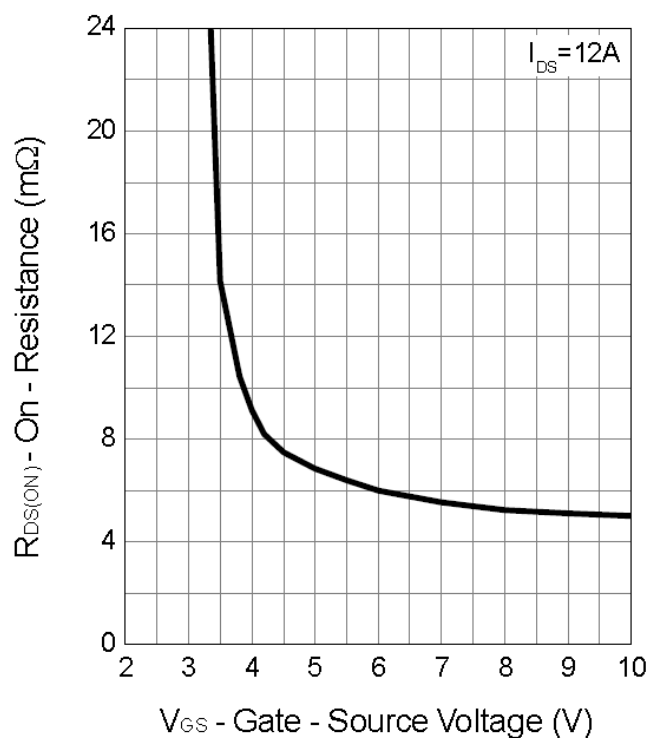


Drain-Source On Resistance

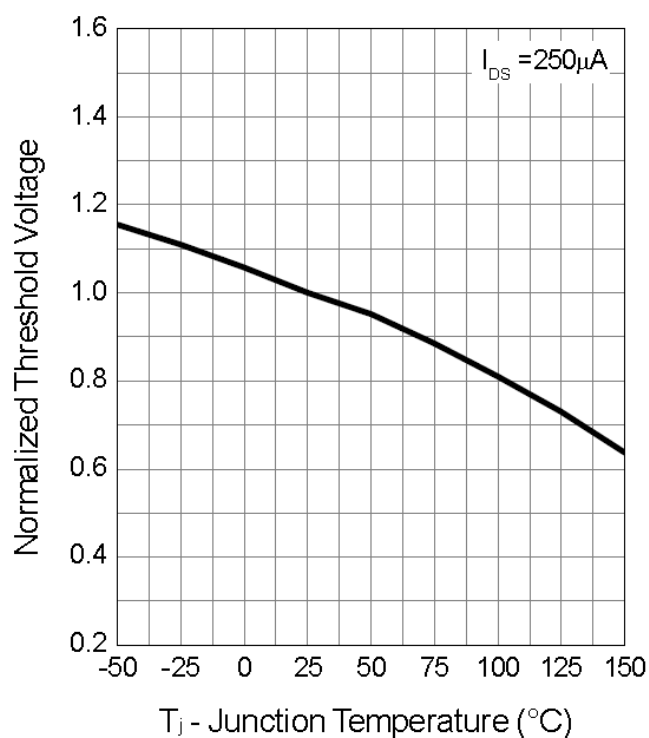


## Typical Operating Characteristics (Cont.)

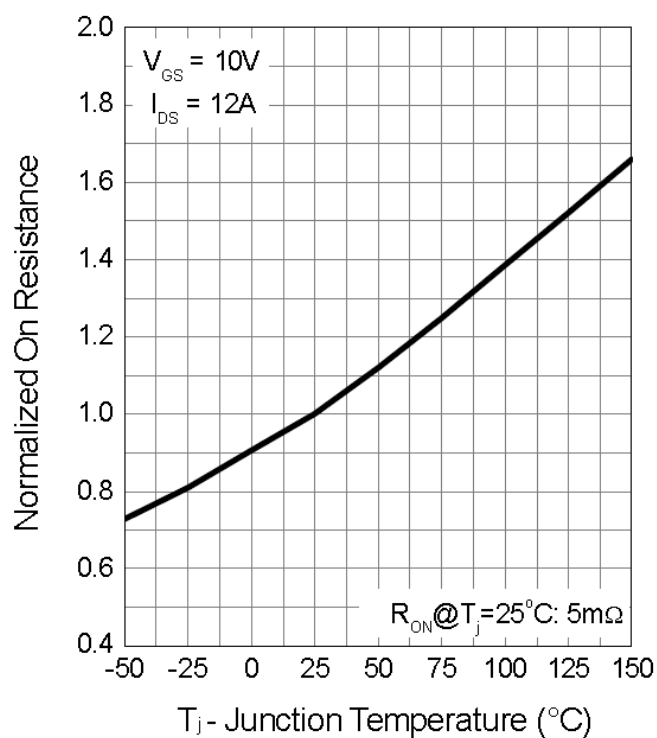
Gate-Source On Resistance



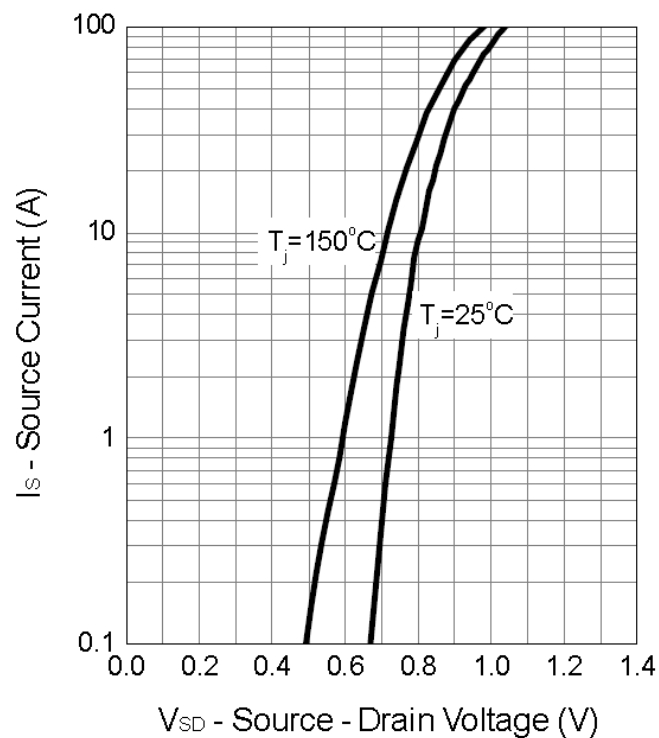
Gate Threshold Voltage



Drain-Source On Resistance

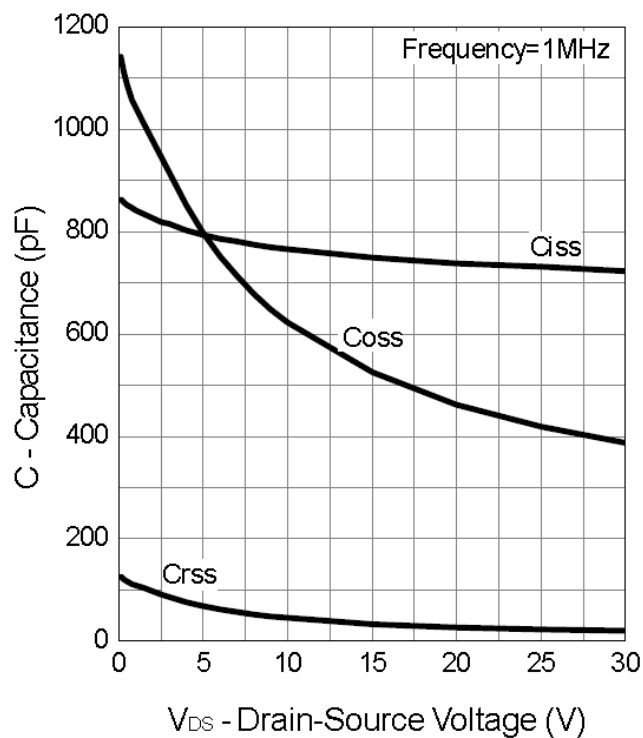


Source-Drain Diode Forward

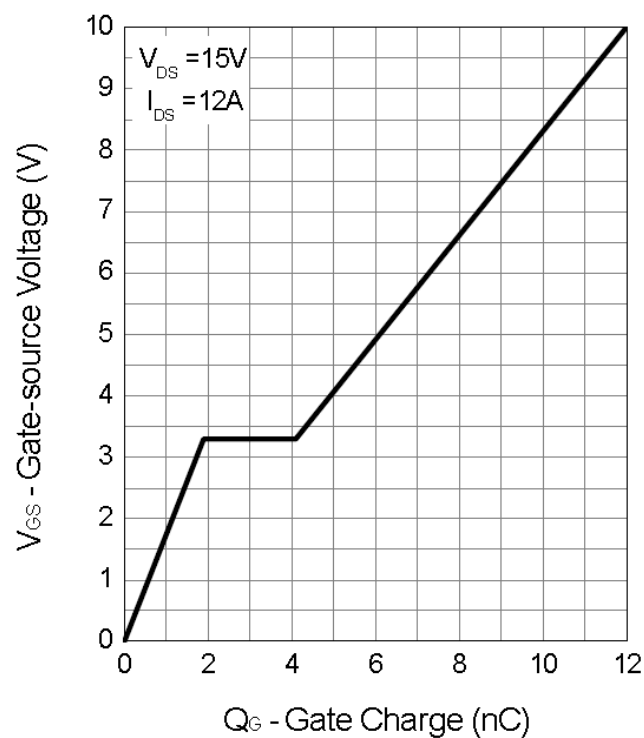


## Typical Operating Characteristics (Cont.)

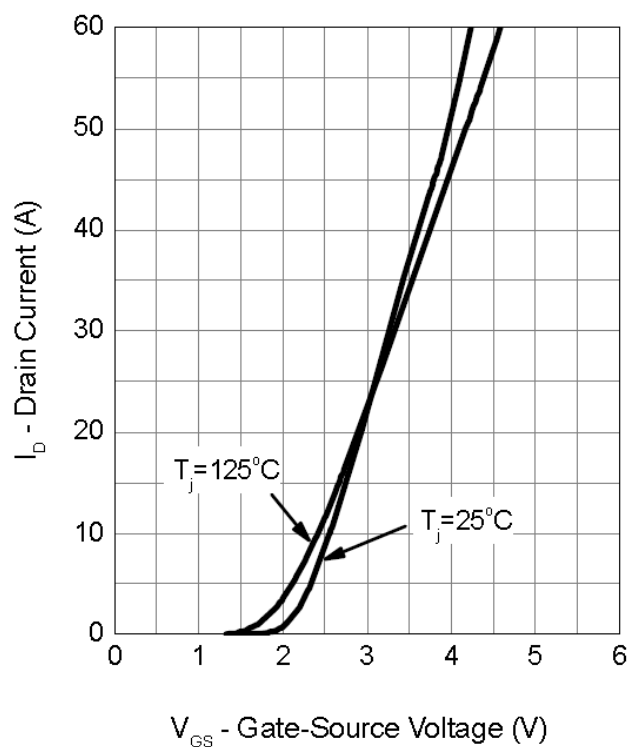
Capacitance



Gate Charge



Transfer Characteristics

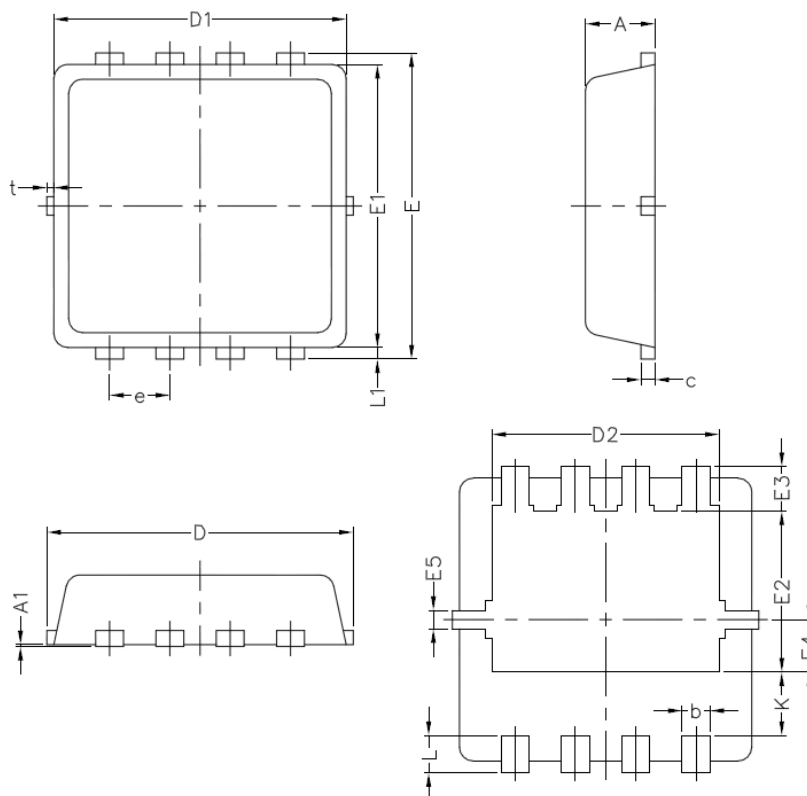


# N-Channel Enhancement Mode MOSFET

TDM3478

## Package Information

PPAK-3\*3-8 Package



Symbol	PPAK-3*3-8(mm)		
	Min	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.3	3.45
D1	3.00	3.15	3.30
D2	2.25	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.68
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.49	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	/	/	0.13